MT18SD-H-T5

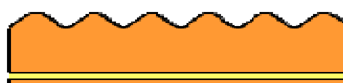
MITSUI KINZOKU

- MicroThin為附18μm載體銅箔的超薄銅箔。
  MicroThin is ultra thin foil with 18μm carrier foil.
- 適用於無芯封裝基板的工藝 。
  Suitable for core-less process

用途/Application

- IC封裝載板
  /Semiconductor Package
- 無芯封裝基板
  /Core-less substrate

構成/Composition



生產地點/Production Site

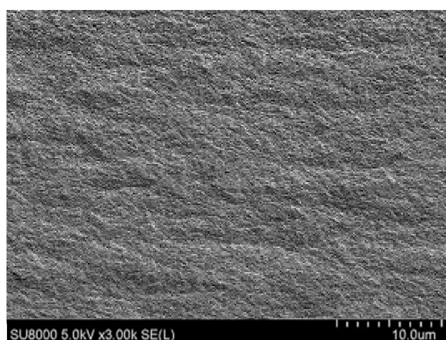
- 日本 / Japan

代表性特性數據/Representive

	μm	Area weight (g/m2)	Deposited side Rz(μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)@FR-4
MT18SD-H-T5	5	40	1	−	−	−

※上述表列為代表性數據非保証值
This is representative data, not guaranteed.

處理面/Laminate side



阻劑面/ resist side